

#### **General Description**

The WST6045 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent  $R_{\text{DSON}}$  and gate charge for most of the small power switching and load switch applications.

The WST6045 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

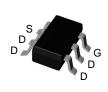
#### **Product Summery**

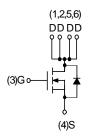
BVDSS	RDSON	ID
60V	40mΩ	5.0A

# **Applications**

- Power management in portable and battery operated products
- One cell battery pack protection

# **SOT-23-6L Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	5.0	Α
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	4.0	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	Α
P <sub>D</sub> @T <sub>A</sub> =25℃	P <sub>D</sub> @T <sub>A</sub> =25℃ Total Power Dissipation <sup>3</sup>		W
T <sub>STG</sub>	T <sub>STG</sub> Storage Temperature Range		$^{\circ}$
T <sub>J</sub>	T <sub>J</sub> Operating Junction Temperature Range		$^{\circ}$

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		110	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		80	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	ource Breakdown Voltage V <sub>GS</sub> =0V , I <sub>D</sub> =250uA				V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient Reference to 25°C , I <sub>D</sub> =1mA			0.028		V/°C	
_	2	V <sub>GS</sub> =10V , I <sub>D</sub> =4.0A		40	50	0	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =3.0A		45	65	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	2.0	3.0	٧	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID -230UA		-3.21		mV/℃	
	Drain Source Loakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance V <sub>DS</sub> =5V , I <sub>D</sub> =5A			12		S	
Rg	Gate Resistance V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz			4		Ω	
$Q_g$	Total Gate Charge (4.5V)			11.5			
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =10V , I <sub>D</sub> =3.5A		2.3		nC	
Q <sub>gd</sub>	Gate-Drain Charge			2.2			
T <sub>d(on)</sub>	Turn-On Delay Time			10			
Tr	Rise Time	$V_{DD}$ =15V , $V_{GEN}$ =10V , $R_G$ =3 $\Omega$		6			
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1.0A ,R <sub>L</sub> =4.2Ω.		21		ns	
T <sub>f</sub>	Fall Time			5			
Ciss	Input Capacitance			540			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		56		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			26			

# **Diode Characteristics**

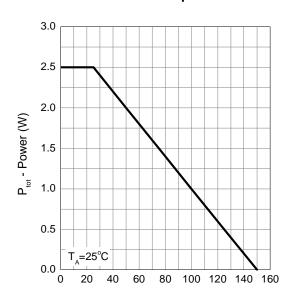
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V =V =0V Force Current			3.0	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			15	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{SD}$ =3.5A , $T_{J}$ =25 $^{\circ}$ C			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			20		nS
Q <sub>rr</sub>	Reverse Recovery Charge	lF=3.5A,dI/dt=100A/μs , T <sub>J</sub> =25℃		20		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150 ℃ junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

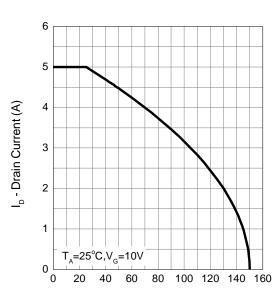
# **Typical Characteristics**

# **Power Dissipation**



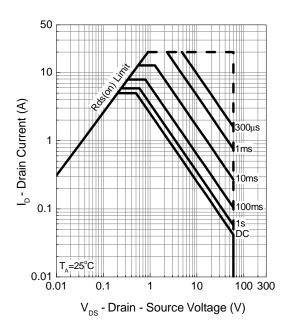
 $T_j$  - Junction Temperature (°C)

#### **Drain Current**

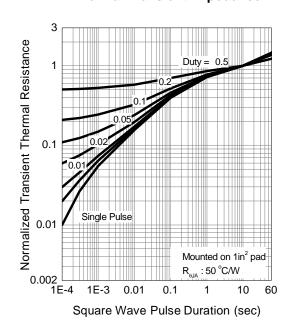


T<sub>i</sub> - Junction Temperature (°C)

# Safe Operation Area

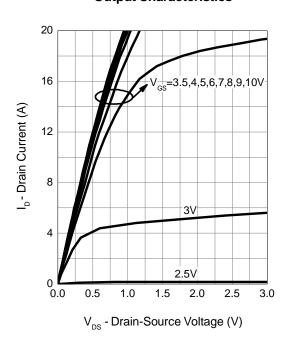


# **Thermal Transient Impedance**

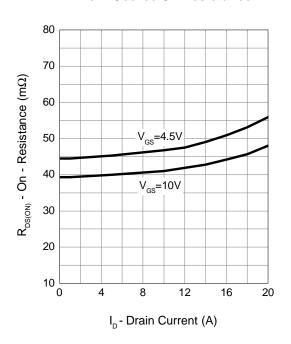


# **Typical Characteristics**

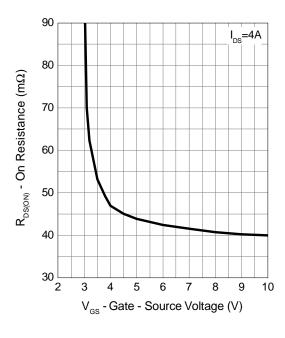
# **Output Characteristics**



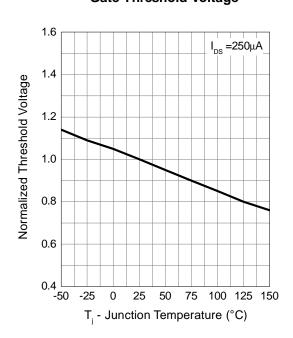
#### **Drain-Source On Resistance**



# **Gate-Source On Resistance**



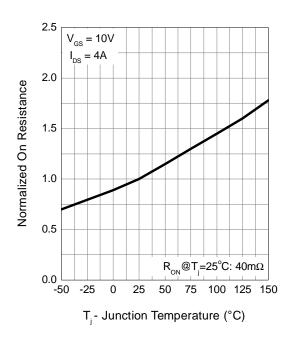
# **Gate Threshold Voltage**



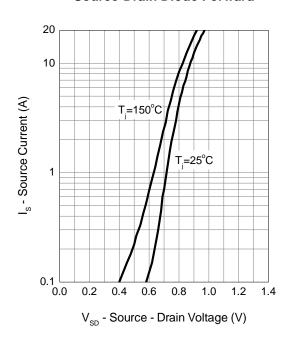


# **Typical Characteristics**

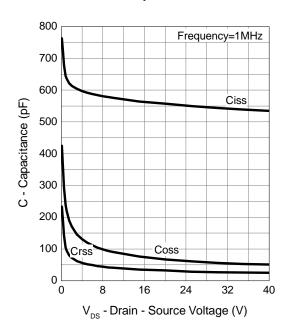
#### **Drain-Source On Resistance**



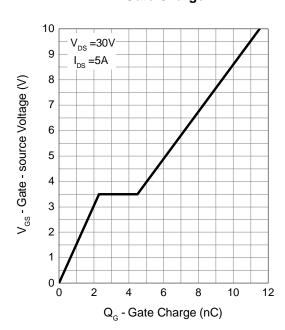
#### **Source-Drain Diode Forward**



#### Capacitance

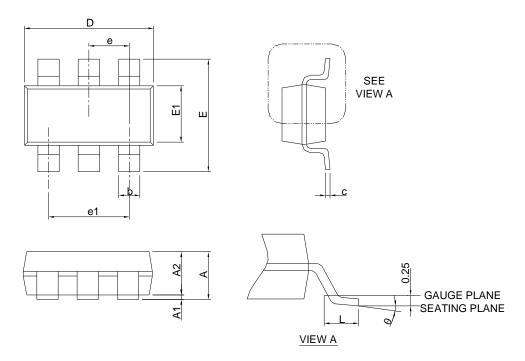


# **Gate Charge**





# Package Information SOT-23-6L

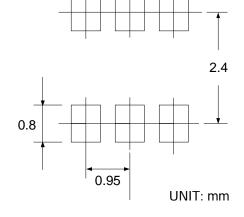


Ş	SOT-23-6L				
S>MBOL	MILLIM	MILLIMETERS		HES	
P	MIN.	MAX.	MIN.	MAX.	
Α	-	1.25	-	0.049	
A1	0.00	0.05	0.000	0.002	
A2	0.90	1.20	0.035	0.047	
b	0.30	0.50	0.012	0.020	
С	0.08	0.22	0.003	0.009	
D	2.70	3.10	0.106	0.122	
Е	2.60	3.00	0.102	0.118	
E1	1.40	1.80	0.055	0.071	
е	0.95	BSC	0.03	7 BSC	
e1	1.90 BSC		0.075 BSC		
L	0.30	0.60	0.012	0.024	
θ	0°	8°	0°	8°	

Note: 1. Follow JEDEC TO-178 AB.

 Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

# RECOMMENDED LAND PATTERN 0.63





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